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FOR IMMEDIATE RELEASE

Molex Debuts Impel High-Speed, High-Performance Backplane Connector System

New system combines industry-leading signal integrity and density with a scalable price and performance path for future data-rate enhancements

WALLDORF, Germany – 21st July, 2014 – Molex Incorporated announces today its Impel™ backplane connector system is available for use with Molex's Backplane Pin Map Configurator. This future-proof connector solution provides equipment manufacturers with the ability to have systems operate at today's data-rates and costs, while providing a migration path for enhancements in the same chassis through Impel daughtercard options.

The Impel connector system delivers industry-leading low cross-talk and high density performance with data-rates up to 40 Gbps for next-generation backplane interconnect solutions. Because it meets all critical architectural needs, including conventional, co-planar, orthogonal midplane and orthogonal direct, it is ideal for telecommunications and data networking applications.

"With many of our customers designing new multi-generation system architectures that include multiple data rate increases over time, our goal was to develop a highly flexible, high-performance connector solution," said Zach Bradford, new product development manager, Molex. "The Impel connector system provides the footprint and interface that allows users to migrate more easily and cost effectively to faster data rates without having to completely redesign their architecture or replace existing data centre hardware."

The Impel conventional connector orientation, with a right angle daughtercard mating to a vertical header, provides 2 to 6 pair options to support price and performance. The 1.90mm conventional solution supports

80 differential pairs per linear inch and the 3.00mm conventional solution enables quad-route capabilities and a lower PCB layer count. In these same configurations, the Impel connector system enables co-planar solutions, which support right angle daughtercard mating to right angle headers for added system scalability. The Impel backplane connector solutions for orthogonal architectures allow for 3 to 6 pair configurations, scaling from 18 to 72 differential pairs per node. Featuring a third generation design, the Impel connector system also provides direct connection of PCBs in an orthogonal orientation to shorten system channel lengths, improve signal integrity channel performance, support open air-flow design and reduce applied cost.

To help customers narrow down the exact products they need, Molex offers a Backplane Pin Map Configurator. Available for free on the Molex website, the tool guides users through a series of inputs to identify backplane parameters and quickly generate a pin map for their backplane application, helping shorten time-to-market and improve overall backplane design and performance.

For additional information please visit: www.molex.com/link/backplane.html. To receive information on other Molex products and industry solutions, please sign up for our e-nouncement newsletter at www.molex.com/link/register.

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About Molex Incorporated

Providing more than connectors, Molex delivers complete interconnect solutions for a number of markets including: data communications, telecommunications, consumer electronics, industrial, automotive, commercial vehicle, aerospace and defence, medical, and lighting. Established in 1938, the company operates 45 manufacturing locations in 17 countries. The Molex website is www.molex.com. Follow us at www.twitter.com/molexconnectors, watch our videos at www.youtube.com/molexconnectors, connect with us at www.facebook.com/molexconnectors and read our blog at www.connector.com.